

# BAS28

## High-speed double diode

Rev. 3 — 22 July 2010

Product data sheet

## 1. Product profile

### 1.1 General description

Two high-speed switching diodes fabricated in planar technology, and encapsulated in a small SOT143B Surface-Mounted Device (SMD) plastic package. The diodes are not connected.

### 1.2 Features and benefits

- High switching speed:  $t_{rr} \leq 4$  ns
- Reverse voltage:  $V_R \leq 75$  V
- Repetitive peak reverse voltage:  $V_{RRM} \leq 85$  V
- Repetitive peak forward current:  $I_{FRM} \leq 500$  mA
- AEC-Q101 qualified
- Small SMD package

### 1.3 Applications

- High-speed switching in e.g. surface-mounted circuits

### 1.4 Quick reference data

Table 1. Quick reference data

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
<b>Per diode</b>						
$I_F$	forward current		[1]	-	215	mA
$I_R$	reverse current	$V_R = 75$ V	-	-	1	$\mu$ A
$V_R$	reverse voltage		-	-	75	V
$t_{rr}$	reverse recovery time		[2]	-	4	ns

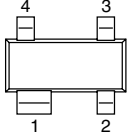
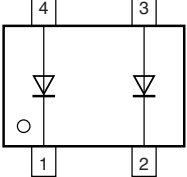
[1] Device mounted on an FR4 Printed-Circuit Board (PCB).

[2] When switched from  $I_F = 10$  mA to  $I_R = 10$  mA;  $R_L = 100$   $\Omega$ ; measured at  $I_R = 1$  mA.



## 2. Pinning information

Table 2. Pinning

Pin	Description	Simplified outline	Graphic symbol
1	cathode (diode 1)		
2	cathode (diode 2)		
3	anode (diode 2)		
4	anode (diode 1)		

006aab100

## 3. Ordering information

Table 3. Ordering information

Type number	Package		
	Name	Description	Version
BAS28	-	plastic surface-mounted package; 4 leads	SOT143B

## 4. Marking

Table 4. Marking codes

Type number	Marking code <sup>[1]</sup>
BAS28	JT*

- [1] \* = -: made in Hong Kong  
 \* = p: made in Hong Kong  
 \* = t: made in Malaysia  
 \* = W: made in China

## 5. Limiting values

**Table 5. Limiting values**

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit
<b>Per diode</b>					
$V_{RRM}$	repetitive peak reverse voltage		-	85	V
$V_R$	reverse voltage		-	75	V
$I_F$	forward current		[1] -	215	mA
$I_{FRM}$	repetitive peak forward current		-	500	mA
$I_{FSM}$	non-repetitive peak forward current	square wave	[3]		
		$t_p = 1 \mu\text{s}$	-	4	A
		$t_p = 1 \text{ms}$	-	1	A
		$t_p = 1 \text{s}$	-	0.5	A
<b>Per device</b>					
$P_{tot}$	total power dissipation	$T_{amb} = 25 \text{ }^\circ\text{C}$	[1][2] -	250	mW
$T_j$	junction temperature		-	150	$^\circ\text{C}$
$T_{stg}$	storage temperature		-65	+150	$^\circ\text{C}$

[1] Device mounted on an FR4 PCB.

[2] One diode loaded.

[3]  $T_j = 25 \text{ }^\circ\text{C}$  prior to surge.

## 6. Thermal characteristics

**Table 6. Thermal characteristics**

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
<b>Per device; one diode loaded</b>						
$R_{th(j-a)}$	thermal resistance from junction to ambient	in free air	[1] -	-	500	K/W
$R_{th(j-t)}$	thermal resistance from junction to tie-point		-	-	360	K/W

[1] Device mounted on an FR4 PCB.

## 7. Characteristics

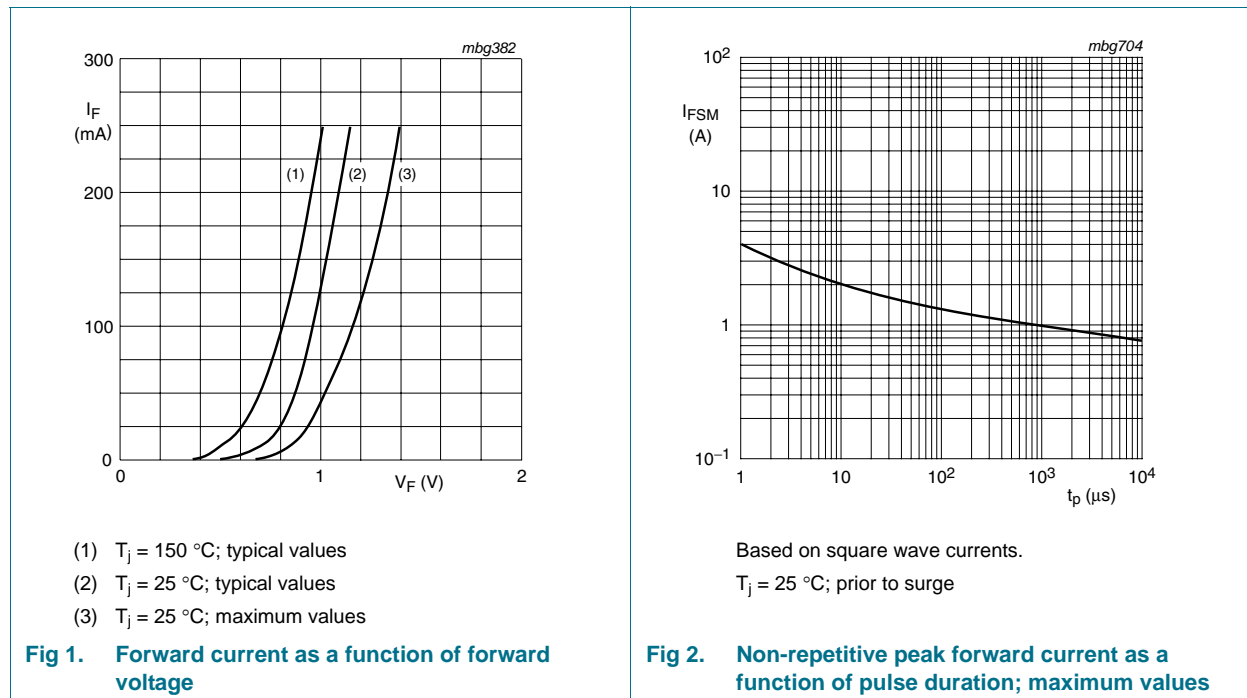
**Table 7. Characteristics**

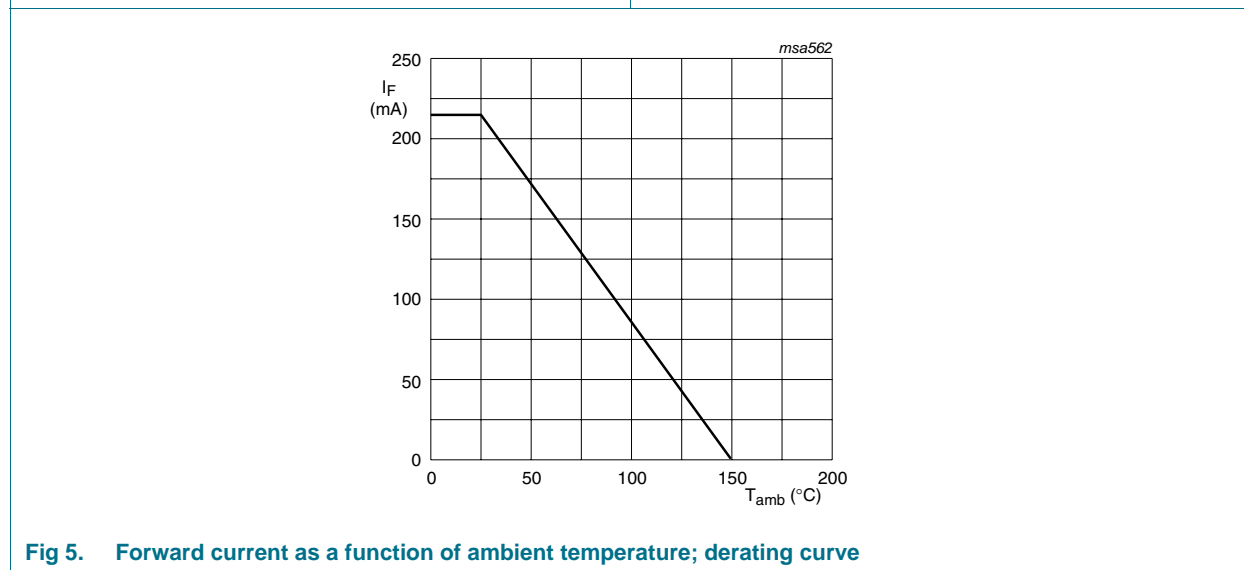
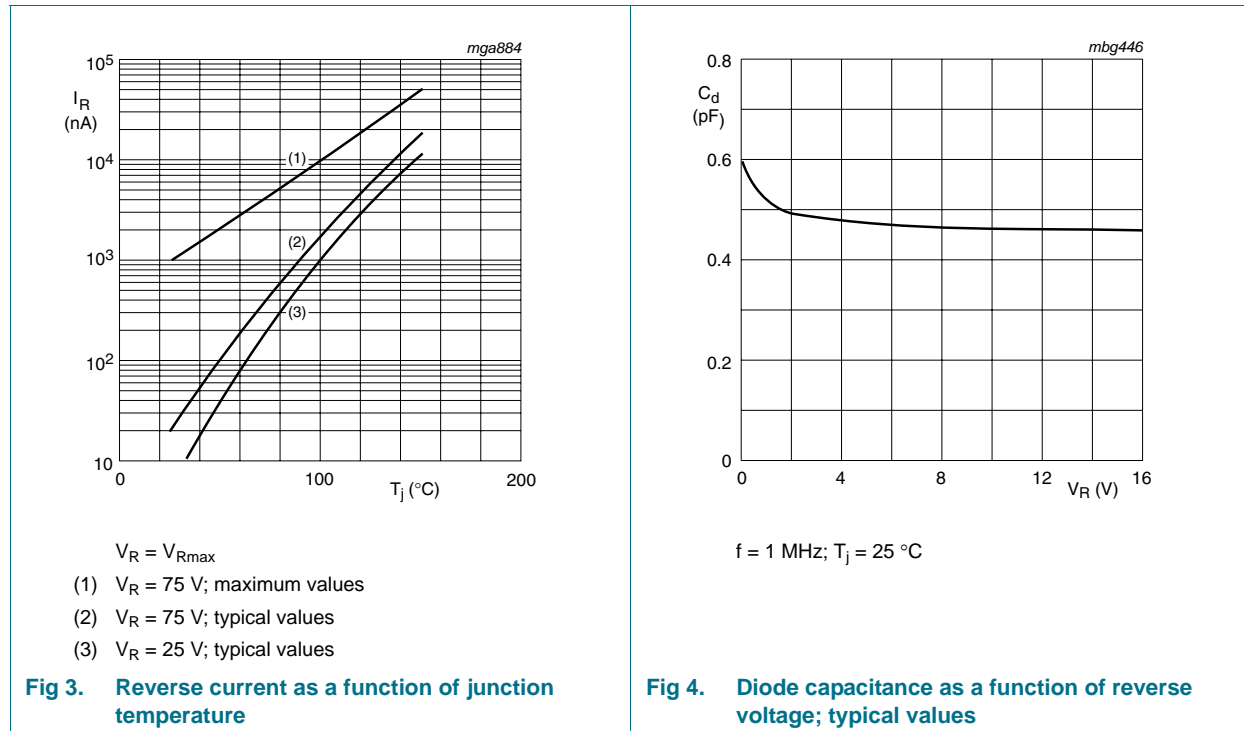
$T_{amb} = 25\text{ }^{\circ}\text{C}$  unless otherwise specified.

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
<b>Per diode</b>						
$V_F$	forward voltage	$I_F = 1\text{ mA}$	-	-	715	mV
		$I_F = 10\text{ mA}$	-	-	855	mV
		$I_F = 50\text{ mA}$	-	-	1	V
		$I_F = 150\text{ mA}$	-	-	1.25	V
$I_R$	reverse current	$V_R = 25\text{ V}$	-	-	30	nA
		$V_R = 75\text{ V}$	-	-	1	$\mu\text{A}$
		$V_R = 25\text{ V}; T_j = 150\text{ }^{\circ}\text{C}$	-	-	30	$\mu\text{A}$
		$V_R = 75\text{ V}; T_j = 150\text{ }^{\circ}\text{C}$	-	-	50	$\mu\text{A}$
$C_d$	diode capacitance	$f = 1\text{ MHz}; V_R = 0\text{ V}$	-	-	1.5	pF
$t_{rr}$	reverse recovery time		[1]	-	4	ns
$V_{FR}$	forward recovery voltage		[2]	-	1.75	V

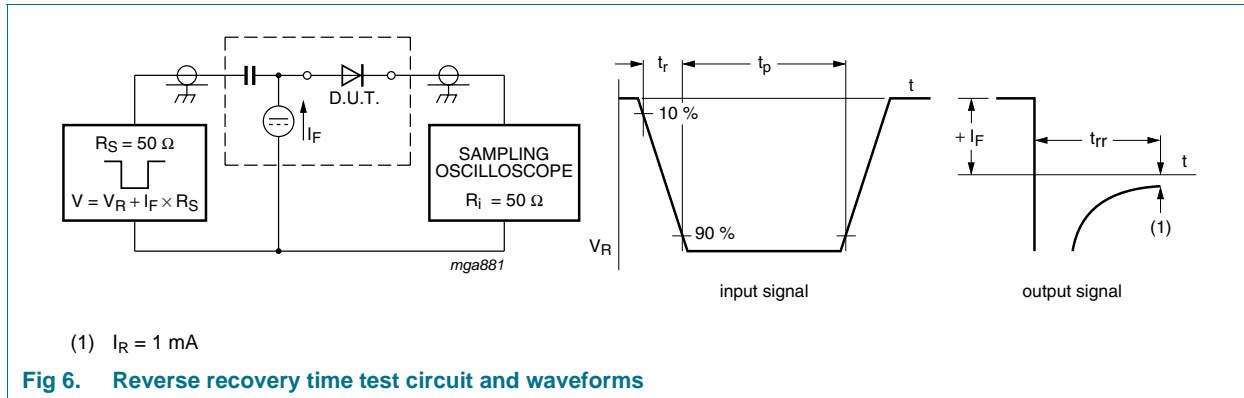
[1] When switched from  $I_F = 10\text{ mA}$  to  $I_R = 10\text{ mA}$ ;  $R_L = 100\text{ }\Omega$ ; measured at  $I_R = 1\text{ mA}$ .

[2] When switched from  $I_F = 10\text{ mA}$ ;  $t_r = 20\text{ ns}$ .

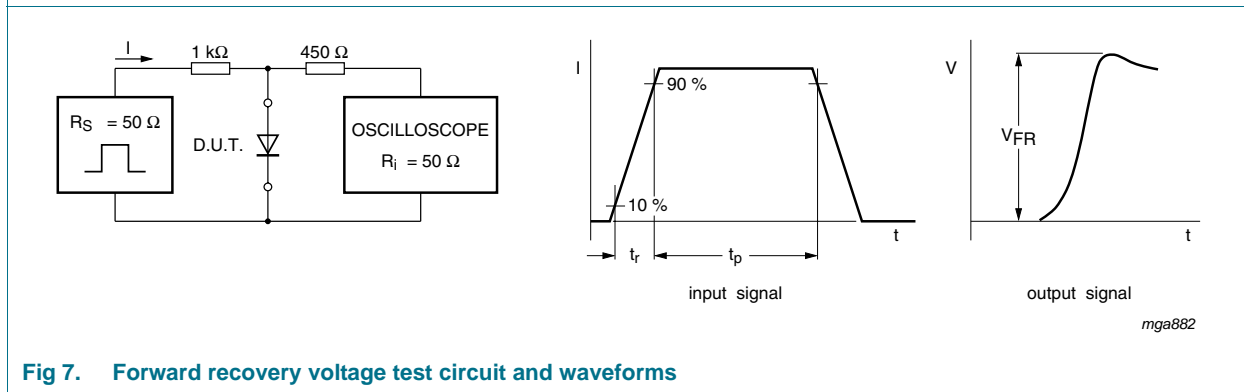




## 8. Test information



**Fig 6. Reverse recovery time test circuit and waveforms**



**Fig 7. Forward recovery voltage test circuit and waveforms**

### 8.1 Quality information

This product has been qualified in accordance with the Automotive Electronics Council (AEC) standard Q101 - *Stress test qualification for discrete semiconductors*, and is suitable for use in automotive applications.

## 9. Package outline

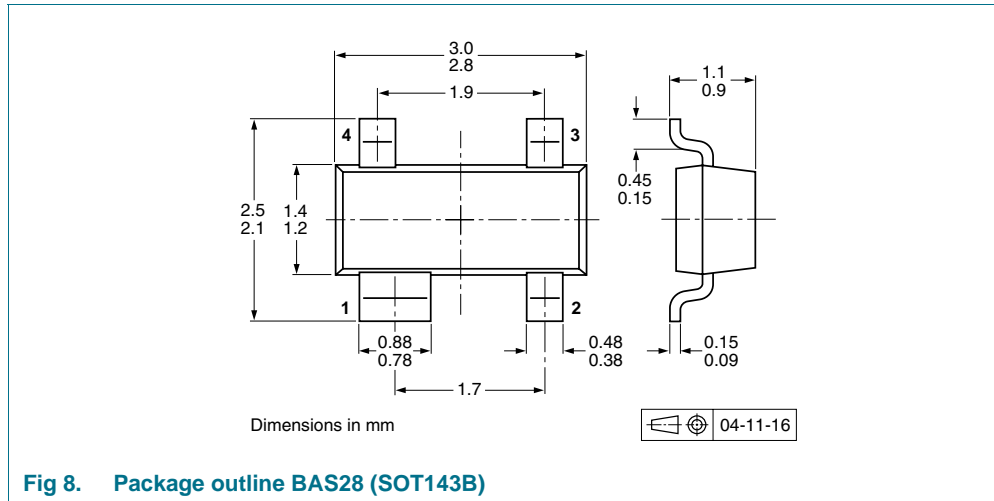


Fig 8. Package outline BAS28 (SOT143B)

## 10. Packing information

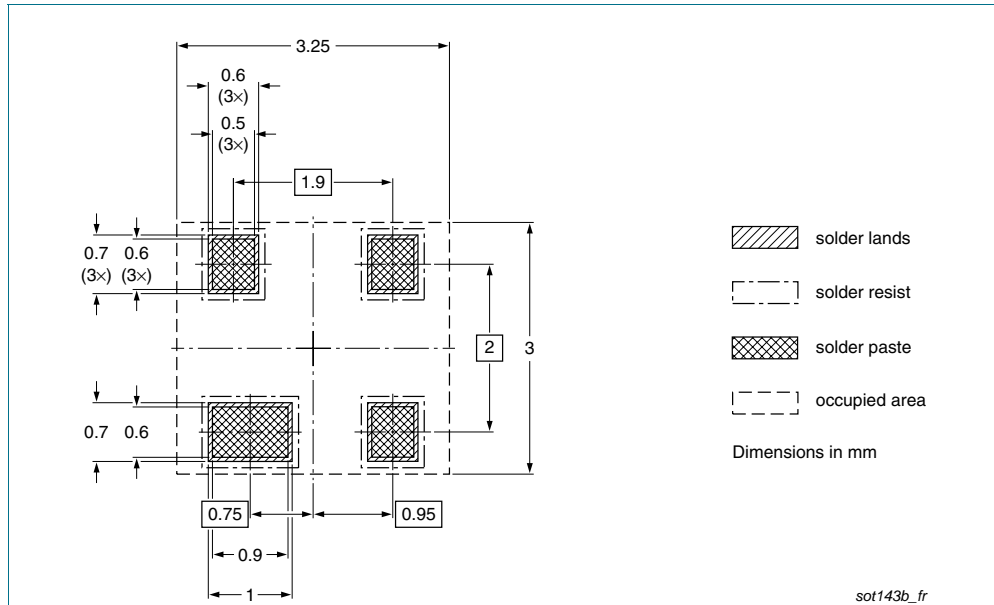
**Table 8. Packing methods**

The indicated -xxx are the last three digits of the 12NC ordering code.<sup>[1]</sup>

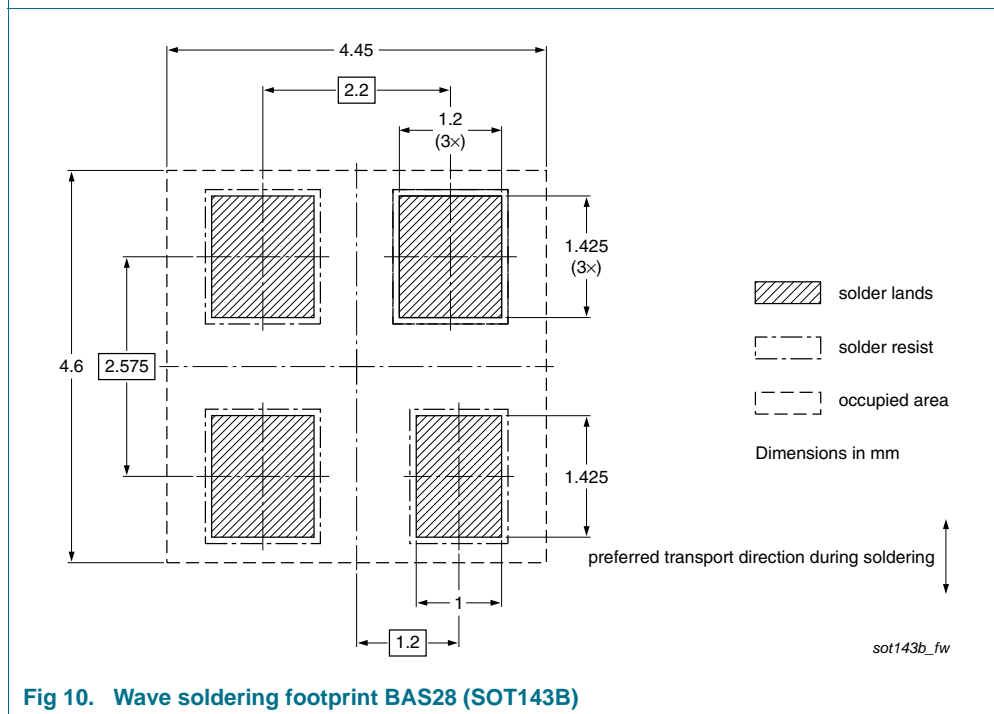
Type number	Package	Description	Packing quantity	
			3000	10000
BAS28	SOT143B	4 mm pitch, 8 mm tape and reel	-215	-235

[1] For further information and the availability of packing methods, see [Section 14](#).

**11. Soldering**



**Fig 9. Reflow soldering footprint BAS28 (SOT143B)**



**Fig 10. Wave soldering footprint BAS28 (SOT143B)**



## 12. Revision history

Table 9. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
BAS28 v.3	20100722	Product data sheet	-	BAS28_2
Modifications:	<ul style="list-style-type: none"> <li>• The format of this data sheet has been redesigned to comply with the new identity guidelines of NXP Semiconductors.</li> <li>• Legal texts have been adapted to the new company name where appropriate.</li> <li>• <a href="#">Section 1.1 "General description"</a>: amended</li> <li>• <a href="#">Section 4 "Marking"</a>: updated</li> <li>• <a href="#">Table 1 "Quick reference data"</a>: added</li> <li>• <a href="#">Section 8 "Test information"</a>: added</li> <li>• <a href="#">Figure 8</a>: superseded by minimized package outline drawing</li> <li>• <a href="#">Section 10 "Packing information"</a>: added</li> <li>• <a href="#">Section 11 "Soldering"</a>: added</li> <li>• <a href="#">Section 13 "Legal information"</a>: updated</li> </ul>			
BAS28_2	19960910	Product specification	-	BAS28_1
BAS28_1	19960403	Product specification	-	-

## 13. Legal information

### 13.1 Data sheet status

Document status <sup>[1][2]</sup>	Product status <sup>[3]</sup>	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

[3] The product status of device(s) described in this document may have changed since this document was published and may differ in case of multiple devices. The latest product status information is available on the Internet at URL <http://www.nxp.com>.

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## 15. Contents

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<b>1</b>	<b>Product profile</b> . . . . .	<b>1</b>
1.1	General description . . . . .	1
1.2	Features and benefits . . . . .	1
1.3	Applications . . . . .	1
1.4	Quick reference data . . . . .	1
<b>2</b>	<b>Pinning information</b> . . . . .	<b>2</b>
<b>3</b>	<b>Ordering information</b> . . . . .	<b>2</b>
<b>4</b>	<b>Marking</b> . . . . .	<b>2</b>
<b>5</b>	<b>Limiting values</b> . . . . .	<b>3</b>
<b>6</b>	<b>Thermal characteristics</b> . . . . .	<b>3</b>
<b>7</b>	<b>Characteristics</b> . . . . .	<b>4</b>
<b>8</b>	<b>Test information</b> . . . . .	<b>6</b>
8.1	Quality information . . . . .	6
<b>9</b>	<b>Package outline</b> . . . . .	<b>7</b>
<b>10</b>	<b>Packing information</b> . . . . .	<b>7</b>
<b>11</b>	<b>Soldering</b> . . . . .	<b>8</b>
<b>12</b>	<b>Revision history</b> . . . . .	<b>9</b>
<b>13</b>	<b>Legal information</b> . . . . .	<b>10</b>
13.1	Data sheet status . . . . .	10
13.2	Definitions . . . . .	10
13.3	Disclaimers . . . . .	10
13.4	Trademarks . . . . .	11
<b>14</b>	<b>Contact information</b> . . . . .	<b>11</b>
<b>15</b>	<b>Contents</b> . . . . .	<b>12</b>

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